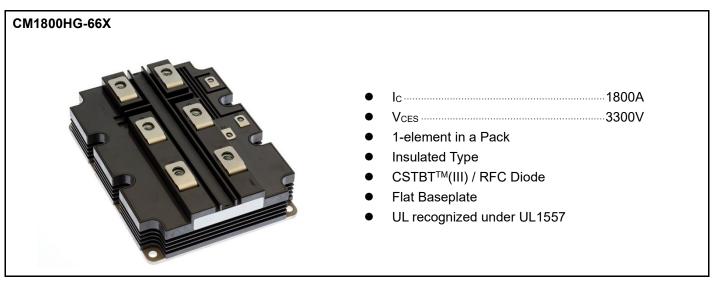


< High Voltage Insulated Gate Bipolar Transistor: HVIGBT >

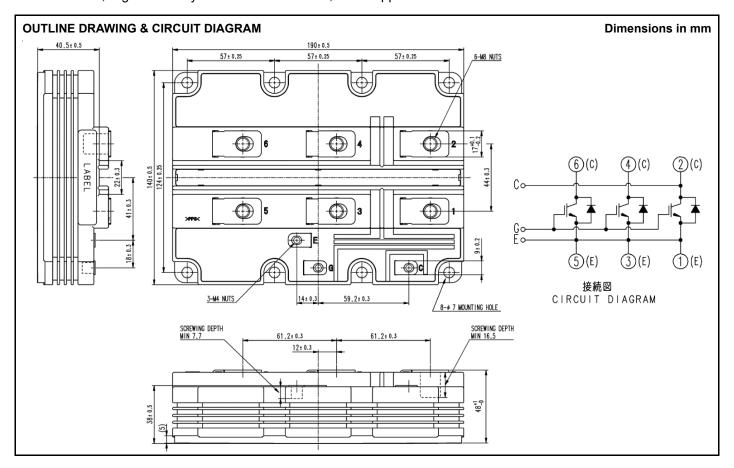
CM1800HG-66X

HIGH POWER SWITCHING USE INSULATED TYPE



APPLICATION

Traction drives, High Reliability Converters / Inverters, DC choppers



HIGH POWER SWITCHING USE INSULATED TYPE

MAXIMUM RATINGS

Symbol	Item	Conditions	Ratings	Unit
\/	Collector emitter veltage	V _{GE} = 0V, T _j = -40+150°C	3300	V
Vces	Collector-emitter voltage	$V_{GE} = 0V, T_j = -50^{\circ}C$	3200	V
V_{GES}	Gate-emitter voltage	$V_{CE} = 0V, T_j = 25^{\circ}C$	± 20	V
Ic	Callastan aumant	DC, T _c = 105°C	1800	Α
I _{CRM}	Collector current	Pulse (Note1)	3600	Α
Ι _Ε	Emitter current (Note2)	DC, T _c = 95°C	1800	Α
I _{ERM}	Emilier current (************************************	Pulse (Note1)	3600	Α
P _{tot}	Maximum power dissipation (Note3)	T _c = 25°C, IGBT part	17800	W
V _{iso}	Isolation voltage	RMS, sinusoidal, f = 60Hz, t = 1 min.	10200	V
Ve	Partial discharge extinction voltage	RMS, sinusoidal, f = 60Hz, Q _{PD} ≤ 10 pC	5100	V
Tj	Junction temperature		− 50 ~ + 150	°C
T _{jop}	Operating junction temperature		− 50 ~ + 150	°C
T _{stg}	Storage temperature		− 55 ~ + 150	°C
t _{psc}	Short circuit pulse width	$V_{CC} = 2500V, V_{CE} \le V_{CES}, V_{GE} = 15V, T_j = 150^{\circ}C$	10	μS

ELECTRICAL CHARACTERISTICS

Cumbal	Itom	Conditions		Limits			1.1
Symbol	Item			Min.	Тур.	Max.	Unit
			T _j = 25 °C	_	_	6.0	
Ices	Collector cutoff current	V _{CE} = V _{CES} , V _{GE} = 0V	T _j = 125 °C	_	6.0	_	mA
			T _j = 150 °C	_	36.0	_	
V _{GE(th)}	Gate-emitter threshold voltage	V_{CE} = 10 V, I_{C} = 180 mA, T_{j} = 25 °	С	6.5	7.0	7.5	V
Iges	Gate leakage current	$V_{GE} = V_{GES}$, $V_{CE} = 0$ V, $T_j = 25$ °C		-0.5	_	0.5	μΑ
Cies	Input capacitance	\(- 40 \\ \\ - 0 \\ f - 400 \\ \\	_	_	208	_	
Coes	Output capacitance	V _{CE} = 10 V, V _{GE} = 0 V, f = 100 kHz T _i = 25 °C	<u>′</u>	_	14.0	_	nF
Cres	Reverse transfer capacitance	1] = 25 C		_	1.9	_	
Q _G	Total gate charge	V _{CC} = 1800 V, I _C = 1800 A, V _{GE} =	±15 V	_	13.5	_	μC
		L 4000 A (Noted)	T _j = 25 °C	_	2.00	_	
V_{CEsat}	Collector-emitter saturation voltage	I _C = 1800 A ^(Note4) V _{GE} = 15 V	T _j = 125 °C	_	2.50	_	V
		VGE - 13 V	T _j = 150 °C	_	2.60	3.10	
t _{d(on)}	Turn-on delay time		T _j = 150 °C	_	_	0.90	μs
tr	Rise time	V _{CC} = 1800 V	T _j = 150 °C	_	_	0.50	μs
	Turn-on switching energy per pulse (Note 5)	I _C = 1800 V V _{GE} = ±15 V	T _j = 25 °C	_	2.75	_	
E _{on(10%)}			T _j = 125 °C	_	3.05	_	J
		$R_{G(on)} = 1.5 \Omega$	T _j = 150 °C	_	3.20	_	
	Turn-on switching energy per pulse (Note 6)	Ls = 150 nH	T _j = 25 °C	_	2.80	_	J
Eon		Inductive load	T _j = 125 °C	_	3.20	_	
			T _j = 150 °C	_	3.35	_	
	Turn-off delay time		T _j = 25 °C	_	2.90	_	
$t_{d(off)}$			T _j = 125 °C	_	3.20	_	μs
			T _j = 150 °C	_	3.20	4.25	
		V _{CC} = 1800 V	T _j = 25 °C	_	0.40	_	
t_f	Fall time	Ic = 1800 A	T _j = 125 °C	_	0.45	_	μs
		V _{GE} = ±15 V	T _j = 150 °C	_	0.50	1.00	
E _{off(10%)}	Turn-off switching energy	$R_{G(off)} = 12 \Omega$	T _j = 25 °C	_	2.40	_	
		Ls = 150 nH	T _j = 125 °C	_	3.15	_	J
, ,	per pulse (Note 5)	Inductive load	T _j = 150 °C	_	3.20	_	
			T _i = 25 °C	_	2.55	_	
E _{off}	Turn-off switching energy		T _i = 125 °C	_	3.20	_	J
-on	per pulse (Note 6)		T _i = 150 °C	_	3.45	_	

HIGH POWER SWITCHING USE INSULATED TYPE

ELECTRICAL CHARACTERISTICS

Cumbal	Itam	Conditions		Limits			Unit
Symbol	Item			Min.	Тур.	Max.	Unit
	Emitter-collector voltage (Note2)	1 1000 A (Noted)	T _j = 25 °C	_	2.20	_	
VEC		I _E = 1800 A ^(Note4) V _{GE} = 0 V	T _j = 125 °C	_	2.40	_	V
		VGE - U V	T _j = 150 °C	_	2.50	3.00	
			T _j = 25 °C	_	1.20	_	
t _{rr}	Reverse recovery time (Note2)		T _j = 125 °C	_	1.35	_	μs
			T _j = 150 °C	_	1.40	_	
			T _j = 25 °C	_	_	_	Α
Irr	Reverse recovery current (Note2)	V_{CC} = 1800 V I_E = 1800 A V_{GE} = ±15 V $R_{G(on)}$ = 1.5 Ω	T _j = 125 °C	_	2200	_	
			T _j = 150 °C	_	2350	_	
	Reverse recovery charge (Note2, 7)		T _j = 25 °C	_	1600	_	μС
Q _{rr(10%)}			T _j = 125 °C	_	2400	_	
			T _j = 150 °C	_	2500	_	
			T _j = 25 °C	_	1800	_	
Qrr	Reverse recovery charge (Note 2,6)	Ls = 150 nH	T _j = 125 °C	_	2600		μC
		Inductive load	T _j = 150 °C	_	2700		
	5		T _j = 25 °C	_	1.85	_	
E _{rec(10%)}	Reverse recovery energy per pulse (Note 2, 5)		T _j = 125 °C	_	2.65		J
	pei puise · · · · ·		T _j = 150 °C	_	3.00	_	
_	Reverse recovery energy per pulse (Note 2,6)		T _j = 25 °C	_	2.00	_	
Erec			T _j = 125 °C	_	2.80		J
	pei puise (=,+/		T _j = 150 °C	_	3.15	_	

THERMAL CHARACTERISTICS

Symbol	Item	Conditions	Limits			Unit
Symbol		Conditions		Тур.	Max.	Offic
R _{th(j-c)Q}	Thermal resistance	Junction to Case, IGBT part	_	_	7.0	K/kW
$R_{th(j-c)D}$	Thermal resistance	Junction to Case, FWDi part	_	_	11.0	K/kW
R _{th(c-s)}	Contact thermal resistance	Case to heat sink $\lambda_{grease} = 1W/m \cdot k$, $D_{(c-s)} = 80 \mu m$	_	5.0	_	K/kW

MECHANICAL CHARACTERISTICS

Cy made al	Item	Conditions	Limits			l lm:4
Symbol			Min.	Тур.	Max.	Unit
Mt		Main terminals screw : M8	7.0	_	19.0	N·m
Ms	Mounting torque	Mounting screw : M6	3.0	_	6.0	N·m
Mt		Auxiliary terminals screw : M4	1.0	_	3.0	N·m
m	Mass		_	1.5	_	kg
CTI	Comparative tracking index		600	_	_	_
da	Clearance		26.0	_	_	mm
ds	Creepage distance		56.0	_	_	mm
L _{P CE}	Parasitic stray inductance		_	13.5		nΗ
R _{CC'+EE'}	Internal lead resistance	T _c = 25 °C	_	0.12		mΩ

Note 1. Pulse width and repetition rate should be such that junction temperature (T_j) does not exceed T_{jopmax} rating.

 $Note 2. \ The \ symbols \ represent \ characteristics \ of \ the \ anti-parallel, \ emitter \ to \ collector \ free-wheel \ diode \ (FWD_i).$

Note3. Junction temperature (T_j) should not exceed T_{jmax} rating (150°C).

Note4. Pulse width and repetition rate should be such as to cause negligible temperature rise.

Note5. The integration range of switching energies is from $10\%V_{CE}$ to $10\%I_{C}(10\%I_{E})$.

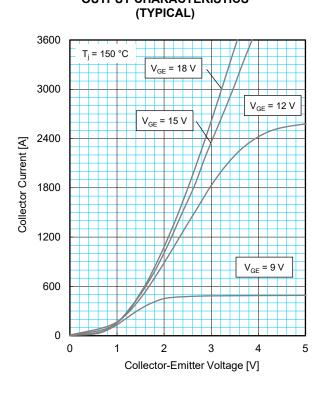
Note6. Definition of all items is according to IEC 60747, unless otherwise specified.

Note7. The integration range of reverse recovery charge is from I_{E} = 0A to 10% $I_{\text{E}}.$

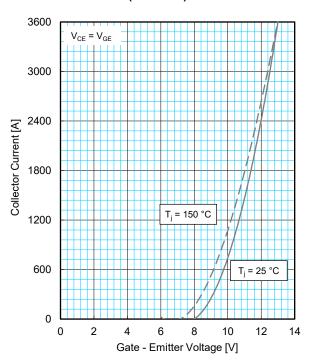
HIGH POWER SWITCHING USE INSULATED TYPE

PERFORMANCE CURVES

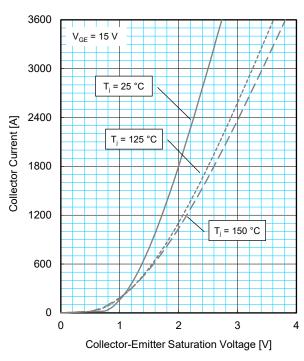
OUTPUT CHARACTERISTICS



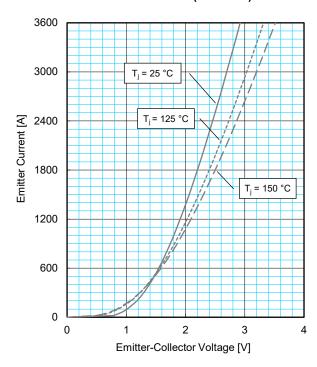
TRANSFER CHARACTERISTICS (TYPICAL)



COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)



FREE-WHEEL DIODE FORWARD CHARACTERISTICS (TYPICAL)

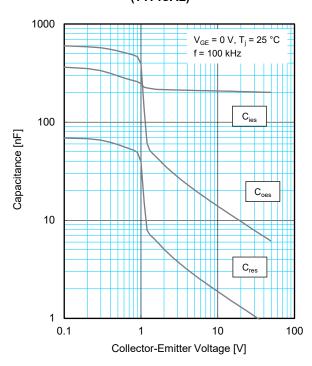


HIGH POWER SWITCHING USE INSULATED TYPE

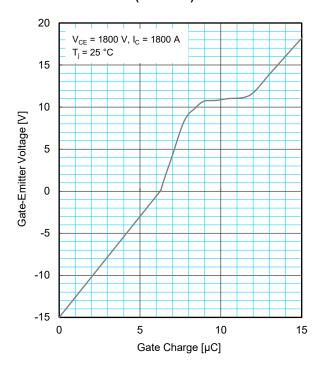
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PERFORMANCE CURVES

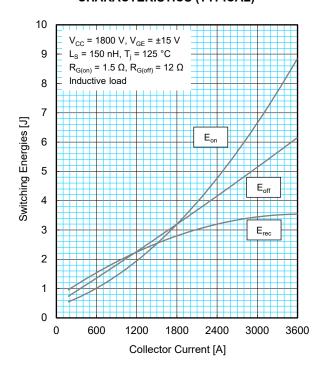
CAPACITANCE CHARACTERISTICS (TYPICAL)



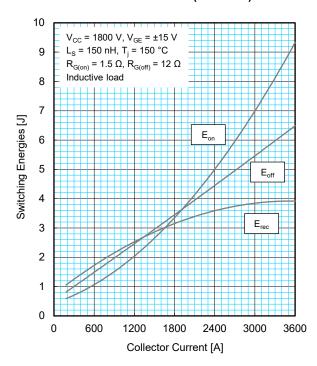
GATE CHARGE CHARACTERISTICS (TYPICAL)



HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS (TYPICAL)



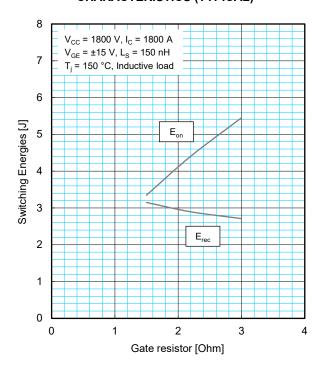
HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS (TYPICAL)



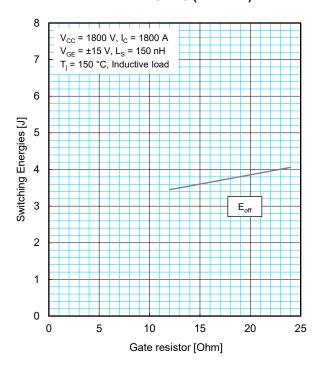
HIGH POWER SWITCHING USE INSULATED TYPE

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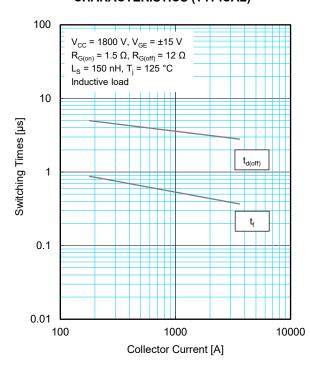
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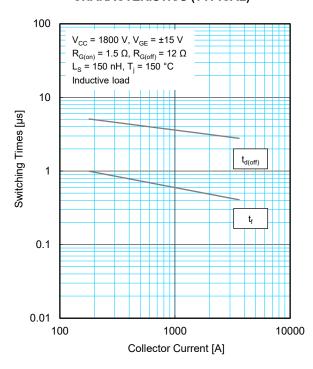
HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS (TYPICAL)



HALF-BRIDGE SWITCHING TIME CHARACTERISTICS (TYPICAL)



HALF-BRIDGE SWITCHING TIME CHARACTERISTICS (TYPICAL)

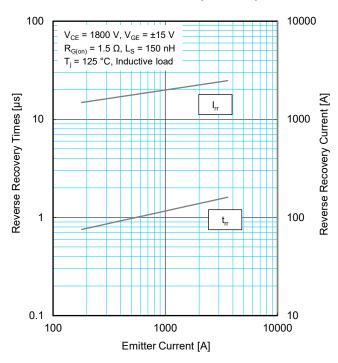


HIGH POWER SWITCHING USE

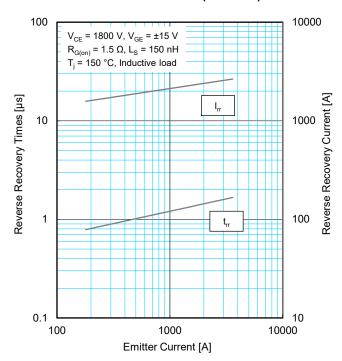
INSULATED TYPE

PERFORMANCE CURVES

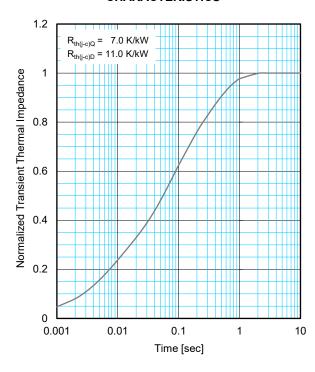
FREE-WHEEL DIODE REVERSE RECOVERY CHARACTERISTICS (TYPICAL)



FREE-WHEEL DIODE REVERSE RECOVERY CHARACTERISTICS (TYPICAL)



TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS



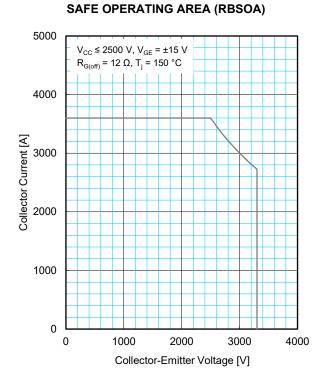
$$Z_{th(j-c)}(t) = \sum_{i=1}^{n} R_{i} \left\{ 1 - \exp^{\left(-\frac{t}{\tau_{i}}\right)} \right\}$$

_		1	2	3	4
	R_i / R_{th}	0.0096	0.1893	0.4044	0.3967
-	τ _i [sec]	0.0001	0.0058	0.0602	0.3512

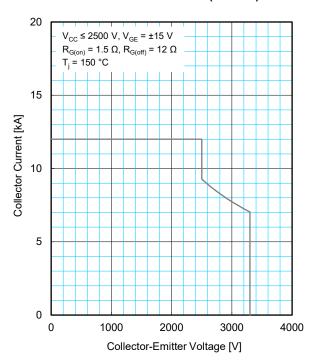
HIGH POWER SWITCHING USE INSULATED TYPE

PERFORMANCE CURVES

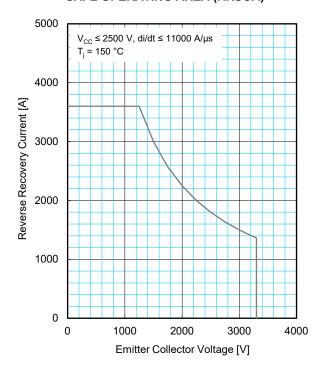
REVERSE BIAS



SHORT CIRCUIT SAFE OPERATING AREA (SCSOA)



FREE-WHEEL DIODE REVERSE RECOVERY SAFE OPERATING AREA (RRSOA)



< High Voltage Insulated Gate Bipolar Transistor: HVIGBT >

CM1800HG-66X

HIGH POWER SWITCHING USE INSULATED TYPE

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HIGH POWER SWITCHING USE INSULATED TYPE

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